

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSP300 H6327	**Issued**	11. August 2021
MA#	MA001622986		
Package	PG-SOT223-4-21	**Weight***	114.06 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.019	1.77	1.77	17706	17706
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		445	
	non noble metal	chromium	7440-47-3	0.152	0.13		1334	
	non noble metal	copper	7440-50-8	50.489	44.28	44.46	442673	444541
wire	non noble metal	copper	7440-50-8	0.016	0.01	0.01	140	140
encapsulation	organic material	carbon black	1333-86-4	0.586	0.51		5141	
	plastics	epoxy resin	-	8.796	7.71		77116	
	inorganic material	silicondioxide	60676-86-0	49.255	43.19	51.41	431851	514108
leadfinish	non noble metal	tin	7440-31-5	1.464	1.28	1.28	12836	12836
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4498	4498
glue	plastics	epoxy resin	-	0.123	0.11		1080	
	noble metal	silver	7440-22-4	0.581	0.51	0.62	5091	6171
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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